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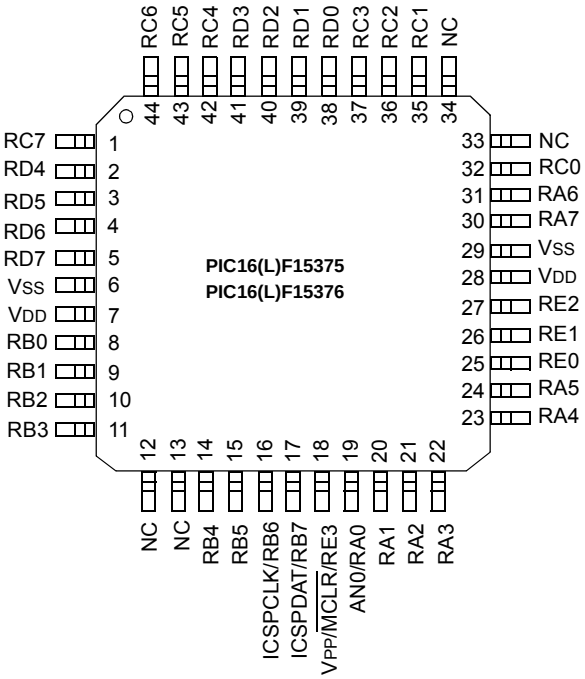
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	44
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 43x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f15386-i-pt

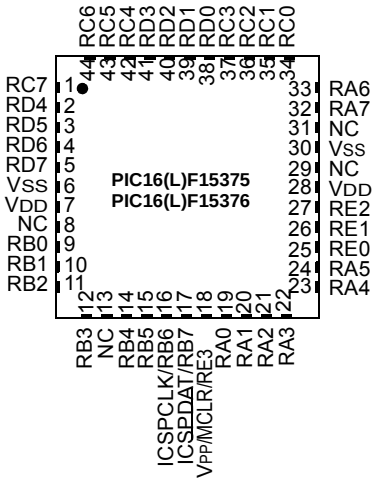
44-PIN TQFP (10x10)



Note 1: See Table 4 for location of all peripheral functions.

2: All VDD and all VSS pins must be connected at the circuit board level. Allowing one or more VSS or VDD pins to float may result in degraded electrical performance or non-functionality.

44-PIN QFN (8x8x0.9)



Note 1: See Table 4 for location of all peripheral functions.

2: All VDD and all VSS pins must be connected at the circuit board level. Allowing one or more VSS or VDD pins to fl may result in degraded electrical performance or non-functionality.

3: The bottom pad of the QFN/UQFN package should be connected to VSS at the circuit board level.

TABLE 1-4: PIC16(L)F15385/86 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RD1/AND1/SDA2(1)/SDI2(1,4)	RD1	TTL/ST	CMOS/OD	General purpose I/O.
	AND1	AN	—	ADC Channel D0 input.
	SDA2(1)	I^2C	OD	MSSP2 I^2C serial data input/output.
	SDI2(1,4)	TTL/ST	—	MSSP2 SPI serial data input (default input location, SDI2 is a PPS remappable input and output).
RD2/AND2	RD2	TTL/ST	CMOS/OD	General purpose I/O.
	AND2	AN	—	ADC Channel D0 input.
RD3/AND3	RD3	TTL/ST	CMOS/OD	General purpose I/O.
	AND3	AN	—	ADC Channel D0 input.
RD4/AND4	RD4	TTL/ST	CMOS/OD	General purpose I/O.
	AND4	AN	—	ADC Channel D0 input.
RD5/AND5	RD5	TTL/ST	CMOS/OD	General purpose I/O.
	AND5	AN	—	ADC Channel D0 input.
RD6/AND6	RD6	TTL/ST	CMOS/OD	General purpose I/O.
	AND6	AN	—	ADC Channel D0 input.
RD7/AND7	RD7	TTL/ST	CMOS/OD	General purpose I/O.
	AND7	AN	—	ADC Channel D0 input.
RE0/ANE0	RE0	TTL/ST	CMOS/OD	General purpose I/O.
	ANE0	AN	—	ADC Channel D0 input.
RE1/ANE1	RE1	TTL/ST	CMOS/OD	General purpose I/O.
	ANE1	AN	—	ADC Channel D0 input.
RE2/ANE2	RE2	TTL/ST	CMOS/OD	General purpose I/O.
	ANE2	AN	—	ADC Channel D0 input.
RE3/$\overline{\text{MCLR}}$/IOCE3	RE3	TTL/ST	—	General purpose input only (when $\overline{\text{MCLR}}$ is disabled by the Configuration bit).
	$\overline{\text{MCLR}}$	ST	—	Master clear input with internal weak pull-up resistor.
	IOCE3	TTL/ST	—	Interrupt-on-change input.
RF0/ANF0	RF0	TTL/ST	CMOS/OD	General purpose I/O.
	ANF0	AN	—	ADC Channel D0 input.
RF1/ANF1	RF1	TTL/ST	CMOS/OD	General purpose I/O.
	ANF1	AN	—	ADC Channel D0 input.
RF2/ANF2	RF2	TTL/ST	CMOS/OD	General purpose I/O.
	ANF2	AN	—	ADC Channel D0 input.
RF3/ANF3	RF3	TTL/ST	CMOS/OD	General purpose I/O.
	ANF3	AN	—	ADC Channel D0 input.
RF4/ANF4	RF4	TTL/ST	CMOS/OD	General purpose I/O.
	ANF4	AN	—	ADC Channel D0 input.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C
HV = High Voltage; XTAL = Crystal levels

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to Table 15-4 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 15-5, Table 15-6 and Table 15-7.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMBus input buffer thresholds.

2.0 GUIDELINES FOR GETTING STARTED WITH PIC16(L)F15356/75/76/85/86 MICROCONTROLLERS

2.1 Basic Connection Requirements

Getting started with the PIC16(L)F15356/75/76/85/86 family of 8-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All VDD and VSS pins (see **Section 2.2 "Power Supply Pins"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.3 "Master Clear (MCLR) Pin"**)

These pins must also be connected if they are being used in the end application:

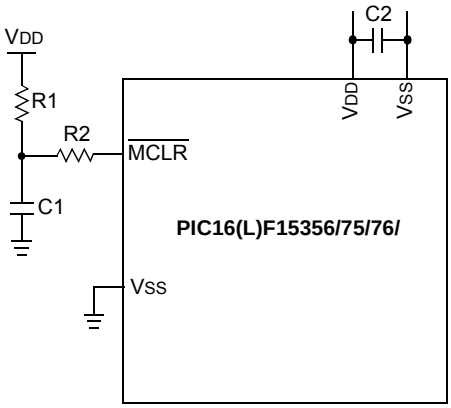
- PGC/PGD pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.4 "ICSP™ Pins"**)
- OSCI and OSCO pins when an external oscillator source is used (see **Section 2.5 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

The minimum mandatory connections are shown in Figure 2-1.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



Key (all values are recommendations):

C1: 10nF, 16V ceramic

C2: 0.1uF, 16V ceramic

R1: 10 kΩ

R2: 100Ω to 470Ω

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins (VDD and VSS) is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-25V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

TABLE 4-4: PIC16(L)F15356/75/76/85/86 MEMORY MAP, BANKS 0-7

BANK 0		BANK 1		BANK 2		BANK 3		BANK 4		BANK 5		BANK 6		BANK 7	
000h	Core Register (Table 4-3)	080h	Core Register (Table 4-3)	100h	Core Register (Table 4-3)	180h	Core Register (Table 4-3)	200h	Core Register (Table 4-3)	280h	Core Register (Table 4-3)	300h	Core Register (Table 4-3)	380h	Core Register (Table 4-3)
00Bh		08Bh		10Bh		18Bh		20Bh		28Bh		30Bh		38Bh	
00Ch	PORTA	08Ch	—	10Ch	—	18Ch	SSP1BUF	20Ch	TMR1L	28Ch	TMR2	30Ch	CCPR1L	38Ch	PWM6DCL
00Dh	PORTB	08Dh	—	10Dh	—	18Dh	SSP1ADD	20Dh	TMR1H	28Dh	PR2	30Dh	CCPR1H	38Dh	PWM6DCH
00Eh	PORTC	08Eh	—	10Eh	—	18Eh	SSP1MASK	20Eh	T1CON	28Eh	T2CON	30Eh	CCP1CON	38Eh	PWM6CON
00Fh	PORTD(2)	08Fh	—	10Fh	—	18Fh	SSP1STAT	20Fh	T1GCON	28Fh	T2HLT	30Fh	CCP1CAP	38Fh	—
010h	PORTE	090h	—	110h	—	190h	SSP1CON1	210h	T1GATE	290h	T2CLK	310h	CCPR2L	390h	—
011h	PORTF(3)	091h	—	111h	—	191h	SSP1CON2	211h	T1CLK	291h	T2ERS	311h	CCPR2H	391h	—
012h	TRISA	092h	—	112h	—	192h	SSP1CON3	212h	—	292h	—	312h	CCP2CON	392h	—
013h	TRISB	093h	—	113h	—	193h	—	213h	—	293h	—	313h	CCP2CAP	393h	—
014h	TRISC	094h	—	114h	—	194h	—	214h	—	294h	—	314h	PWM3DCL	394h	—
015h	TRISD(2)	095h	—	115h	—	195h	—	215h	—	295h	—	315h	PWM3DCH	395h	—
016h	TRISE	096h	—	116h	—	196h	SSP2BUF	216h	—	296h	—	316h	PWM3CON	396h	—
017h	TRISF(3)	097h	—	117h	—	197h	SSP2ADD	217h	—	297h	—	317h	—	397h	—
018h	LATA	098h	—	118h	—	198h	SSP2MASK	218h	—	298h	—	318h	PWM4DCL	398h	—
019h	LATB	099h	—	119h	RC1REG1	199h	SSP2STAT	219h	—	299h	—	319h	PWM4DCH	399h	—
01Ah	LATC	09Ah	—	11Ah	TX1REG1	19Ah	SSP2CON1	21Ah	—	29Ah	—	31Ah	PWM4CON	39Ah	—
01Bh	LATD(2)	09Bh	ADRESL	11Bh	SP1BRG1L	19Bh	SSP2CON2	21Bh	—	29Bh	—	31Bh	—	39Bh	—
01Ch	LATE	09Ch	ADRESH	11Ch	SP1BRG1H	19Ch	SSP2CON3	21Ch	—	29Ch	—	31Ch	PWM5DCL	39Ch	—
01Dh	LATF(3)	09Dh	ADCON0	11Dh	RC1STA1	19Dh	—	21Dh	—	29Dh	—	31Dh	PWM5DCH	39Dh	—
01Eh	—	09Eh	ADCON1	11Eh	TX1STA1	19Eh	—	21Eh	—	29Eh	—	31Eh	PWM5CON	39Eh	—
01Fh	—	09Fh	ADACT	11Fh	BAUD1CON1	19Fh	—	21Fh	—	29Fh	—	31Fh	—	39Fh	—
020h	General Purpose Register 96 Bytes	0A0h	General Purpose Register 80 Bytes	120h	General Purpose Register 80 Bytes	1A0h	General Purpose Register 80 Bytes	220h	General Purpose Register 80 Bytes	2A0h	General Purpose Register 80 Bytes	320h	General Purpose Register 80 Bytes	3A0h	General Purpose Register 80 Bytes
07Fh		0EFh		16Fh		1EFh		26Fh		2EFh		36Fh		3EFh	
		0F0h	Common RAM Accesses 70h-7Fh	170h	Common RAM Accesses 70h-7Fh	1F0h	Common RAM Accesses 70h-7Fh	270h	Common RAM Accesses 70h-7Fh	2F0h	Common RAM Accesses 70h-7Fh	370h	Common RAM Accesses 70h-7Fh	3F0h	Common RAM Accesses 70h-7Fh
		0FFh		17Fh		1FFh		27Fh		2FFh		37Fh		3FFh	

Note 1: Unimplemented locations read as '0'.

2: Present only in PIC16(L)F15375/76/85/86.

3: Present only in PIC16(L)F15385/86.

TABLE 4-11: SPECIAL FUNCTION REGISTER SUMMARY BANKS 0-63 (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on: MCLR
Bank 8-10											
CPU CORE REGISTERS; see Table 4-3 for specifics											
x0Ch/ x8Ch — x1Fh/ x9Fh	—	Unimplemented									

Legend: x = unknown, u = unchanged, q = depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

5.0 DEVICE CONFIGURATION

Device configuration consists of the Configuration Words, User ID, Device ID, Device Information Area (DIA), (see **Section 6.0 "Device Information Area"**), and the Device Configuration Information (DCI) regions, (see **Section 7.0 "Device Configuration Information"**).

5.1 Configuration Words

The devices have several Configuration Words starting at address 8007h. The Configuration bits establish configuration values prior to the execution of any software; Configuration bits enable or disable device-specific features.

In terms of programming, these important Configuration bits should be considered:

1. LVP: Low-Voltage Programming Enable bit

- 1 = ON – Low-Voltage Programming is enabled. $\overline{MCLR}$/V_{PP} pin function is $\overline{MCLR}$. MCLRE Configuration bit is ignored.
- 0 = OFF – HV on $\overline{MCLR}$/V_{PP} must be used for programming.

2. CP: User Nonvolatile Memory (NVM) Program Memory Code Protection bit

- 1 = OFF – User NVM code protection disabled
- 0 = ON – User NVM code protection enabled

REGISTER 5-3: CONFIGURATION WORD 3: WINDOWED WATCHDOG (CONTINUED)

bit 4-0 **WDTCPS<4:0>**: WDT Period Select bits

WDTCPS	WDTPS at POR				Software Control of WDTPS?
	Value	Divider Ratio		Typical Time Out (F_{IN} = 31 kHz)	
11111(1)	01011	1:65536	2^{16}	2 s	Yes
11110 ... 10011	11110 ... 10011	1:32	2^5	1 ms	No
10010	10010	1:8388608	2^{23}	256 s	No
10001	10001	1:4194304	2^{22}	128 s	
10000	10000	1:2097152	2^{21}	64 s	
01111	01111	1:1048576	2^{20}	32 s	
01110	01110	1:524299	2^{19}	16 s	
01101	01101	1:262144	2^{18}	8 s	
01100	01100	1:131072	2^{17}	4 s	
01011	01011	1:65536	2^{16}	2 s	
01010	01010	1:32768	2^{15}	1 s	
01001	01001	1:16384	2^{14}	512 ms	
01000	01000	1:8192	2^{13}	256 ms	
00111	00111	1:4096	2^{12}	128 ms	
00110	00110	1:2048	2^{11}	64 ms	
00101	00101	1:1024	2^{10}	32 ms	
00100	00100	1:512	2^9	16 ms	
00011	00011	1:256	2^8	8 ms	
00010	00010	1:128	2^7	4 ms	
00001	00001	1:64	2^6	2 ms	
00000	00000	1:32	2^5	1 ms	

Note 1: 0b11111 is the default value of the WDTCPS bits.

REGISTER 5-7: REVISIONID: REVISION ID REGISTER

R	R	R	R	R	R	R	R	R	R	R	R	R	R
1	0	MJRREV<5:0>						MNRREV<5:0>					
bit 13													bit 0

Legend:			
	R = Readable bit		
	'0' = Bit is cleared	'1' = Bit is set	x = Bit is unknown

bit 13-12 **Fixed Value**: Read-only bits
These bits are fixed with value '10' for all devices included in this data sheet.

bit 11-6 **MJRREV<5:0>**: Major Revision ID bits
These bits are used to identify a major revision.

bit 5-0 **MNRREV<5:0>**: Minor Revision ID bits
These bits are used to identify a minor revision.

9.2 Clock Source Types

Clock sources can be classified as external or internal.

External clock sources rely on external circuitry for the clock source to function. Examples are: oscillator modules (ECH, ECM, ECL mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes).

Internal clock sources are contained within the oscillator module. The internal oscillator block has two internal oscillators and a dedicated Phase Lock Loop (PLL) that are used to generate internal system clock sources. The High-Frequency Internal Oscillator (HFINTOSC) can produce a range from 1 to 32 MHz. The Low-Frequency Internal Oscillator (LFINTOSC) generates a 31 kHz frequency. The external oscillator block can also be used with the PLL. See **Section 9.2.1.4 "4x PLL"** for more details.

The system clock can be selected between external or internal clock sources via the NOSC bits in the OSCCON1 register. See **Section 9.3 "Clock Switching"** for additional information.

9.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the RSTOSC<2:0> bits in the Configuration Words to select an external clock source that will be used as the default system clock upon a device Reset
- Write the NOSC<2:0> and NDIV<4:0> bits in the OSCCON1 register to switch the system clock source

See **Section 9.3 "Clock Switching"** for more information.

9.2.1.1 EC Mode

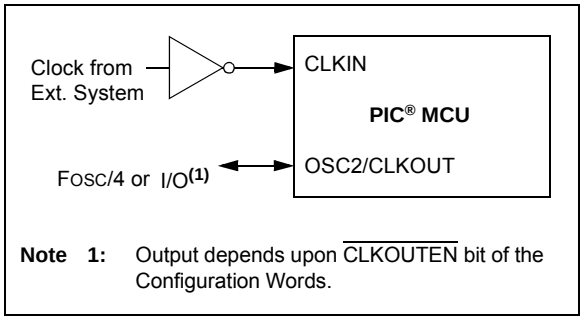
The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. Figure 9-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through Configuration Words:

- ECH – High power, ≤ 32 MHz
- ECM – Medium power, ≤ 8 MHz
- ECL – Low power, ≤ 0.5 MHz

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 9-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Output depends upon $\overline{\text{CLKOUTEN}}$ bit of the Configuration Words.

9.2.1.2 LP, XT, HS Modes

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 9-3). The three modes select a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive crystals and resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 9-3 and Figure 9-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

REGISTER 14-11: LATB: PORTB DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATB<7:0>**: RB<7:0> Output Latch Value bits(1)

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register returns actual I/O pin values.

REGISTER 14-12: ANSELB: PORTB ANALOG SELECT REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
ANSB7	ANSB6	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **ANSB<7:0>**: Analog Select between Analog or Digital Function on pins RB<7:0>, respectively
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.
0 = Digital I/O. Pin is assigned to port or digital special function.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

REGISTER 14-15: SLRCONB: PORTB SLEW RATE CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
SLRB7	SLRB6	SLRB5	SLRB4	SLRB3	SLRB2	SLRB1	SLRB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **SLRB<7:0>:** PORTB Slew Rate Enable bits
For RB<7:0> pins, respectively
1 = Port pin slew rate is limited
0 = Port pin slews at maximum rate

REGISTER 14-16: INLVLB: PORTB INPUT LEVEL CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
INLVLB7	INLVLB6	INLVLB5	INLVLB4	INLVLB3	INLVLB2	INLVLB1	INLVLB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **INLVLB<7:0>:** PORTB Input Level Select bits
For RB<7:0> pins, respectively
1 = ST input used for PORT reads and interrupt-on-change
0 = TTL input used for PORT reads and interrupt-on-change

TABLE 14-3: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	206
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	206
LATB	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	207
ANSELB	ANSB7	ANSB6	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	207
WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	208
ODCONB	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	208
SLRCONB	SLRB7	SLRB6	SLRB5	SLRB4	SLRB3	SLRB2	SLRB1	SLRB0	209
INLVLB	INLVLB7	INLVLB6	INLVLB5	INLVLB4	INLVLB3	INLVLB2	INLVLB1	INLVLB0	209

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by PORTB.

14.12 PORTF Registers

Note: Present only on PIC16(L)F15385/86.

14.12.1 DATA REGISTER

PORTF is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISF (Register 14-42). Setting a TRISF bit (= 1) will make the corresponding PORTF pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISF bit (= 0) will make the corresponding PORTF pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Figure 14-1 shows how to initialize an I/O port.

Reading the PORTF register (Register 14-41) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATF).

The PORT data latch LATF (Register 14-43) holds the output port data, and contains the latest value of a LATF or PORTF write.

14.12.2 DIRECTION CONTROL

The TRISF register (Register 14-42) controls the PORTF pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISF register are maintained set when using them as analog inputs. I/O pins configured as analog inputs always read '0'.

14.12.3 INPUT THRESHOLD CONTROL

The INLVLF register (Register 14-48) controls the input voltage threshold for each of the available PORTF input pins. A selection between the Schmitt Trigger CMOS or the TTL Compatible thresholds is available. The input threshold is important in determining the value of a read of the PORTF register and also the level at which an interrupt-on-change occurs, if that feature is enabled. See Table 37-4 for more information on threshold levels.

Note: Changing the input threshold selection should be performed while all peripheral modules are disabled. Changing the threshold level during the time a module is active may inadvertently generate a transition associated with an input pin, regardless of the actual voltage level on that pin.

14.12.4 OPEN-DRAIN CONTROL

The ODCONF register (Register 14-46) controls the open-drain feature of the port. Open-drain operation is independently selected for each pin. When an ODCONF bit is set, the corresponding port output becomes an open-drain driver capable of sinking current only. When an ODCONF bit is cleared, the corresponding port output pin is the standard push-pull drive capable of sourcing and sinking current.

Note: It is not necessary to set open-drain control when using the pin for I^2C; the I^2C module controls the pin and makes the pin open-drain.

14.12.5 SLEW RATE CONTROL

The SLRCONF register (Register 14-47) controls the slew rate option for each port pin. Slew rate control is independently selectable for each port pin. When an SLRCONF bit is set, the corresponding port pin drive is slew rate limited. When an SLRCONF bit is cleared, The corresponding port pin drive slews at the maximum rate possible.

14.12.6 ANALOG CONTROL

The ANSELF register (Register 14-44) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELF bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELF bits has no effect on digital output functions. A pin with TRIS clear and ANSELF set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note: The ANSELF bits default to the Analog mode after Reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software.

14.12.7 WEAK PULL-UP CONTROL

The WPUF register (Register 14-45) controls the individual weak pull-ups for each port pin.

14.12.8 PORTF FUNCTIONS AND OUTPUT PRIORITIES

Each pin defaults to the PORT latch data after Reset. Other output functions are selected with the peripheral pin select logic. See **Section 15.0 "Peripheral Pin Select (PPS) Module"** for more information.

Analog input functions, such as ADC and comparator inputs, are not shown in the peripheral pin select lists. Digital output functions may continue to control the pin when it is in Analog mode.

17.0 INTERRUPT-ON-CHANGE

All pins on ports A, B and C and lower four bits of PORTE can be configured to operate as Interrupt-on-Change (IOC) pins. An interrupt can be generated by detecting a signal that has either a rising edge or a falling edge. Any individual pin, or combination of pins, can be configured to generate an interrupt. The interrupt-on-change module has the following features:

- Interrupt-on-Change enable (Master Switch)
- Individual pin configuration
- Rising and falling edge detection
- Individual pin interrupt flags

Figure 17-1 is a block diagram of the IOC module.

17.1 Enabling the Module

To allow individual pins to generate an interrupt, the IOCIE bit of the PIE0 register must be set. If the IOCIE bit is disabled, the edge detection on the pin will still occur, but an interrupt will not be generated.

17.2 Individual Pin Configuration

For each pin, a rising edge detector and a falling edge detector are present. To enable a pin to detect a rising edge, the associated bit of the IOCxP register is set. To enable a pin to detect a falling edge, the associated bit of the IOCxN register is set.

A pin can be configured to detect rising and falling edges simultaneously by setting the associated bits in both of the IOCxP and IOCxN registers.

17.3 Interrupt Flags

The bits located in the IOCxF registers are status flags that correspond to the interrupt-on-change pins of each port. If an expected edge is detected on an appropriately enabled pin, then the status flag for that pin will be set, and an interrupt will be generated if the IOCIE bit is set. The IOCIF bit of the PIR0 register reflects the status of all IOCxF bits.

17.3.1 CLEARING INTERRUPT FLAGS

The individual status flags, (IOCxF register bits), can be cleared by resetting them to zero. If another edge is detected during this clearing operation, the associated status flag will be set at the end of the sequence, regardless of the value actually being written.

In order to ensure that no detected edge is lost while clearing flags, only AND operations masking out known changed bits should be performed. The following sequence is an example of what should be performed.

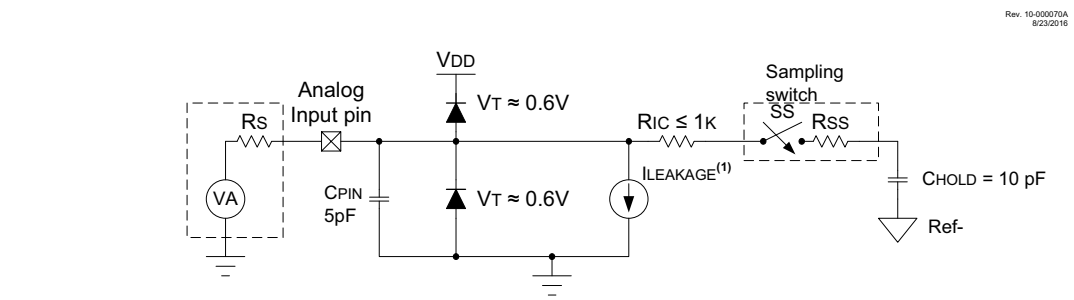
EXAMPLE 17-1: CLEARING INTERRUPT FLAGS (PORTA EXAMPLE)

```
MOVLW  0xff
XORWF  IOCAF, W
ANDWF  IOCAF, F
```

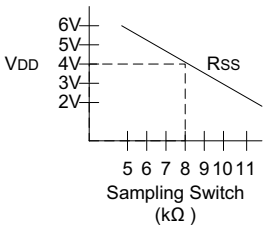
17.4 Operation in Sleep

The interrupt-on-change interrupt event will wake the device from Sleep mode, if the IOCIE bit is set.

FIGURE 20-4: ANALOG INPUT MODEL

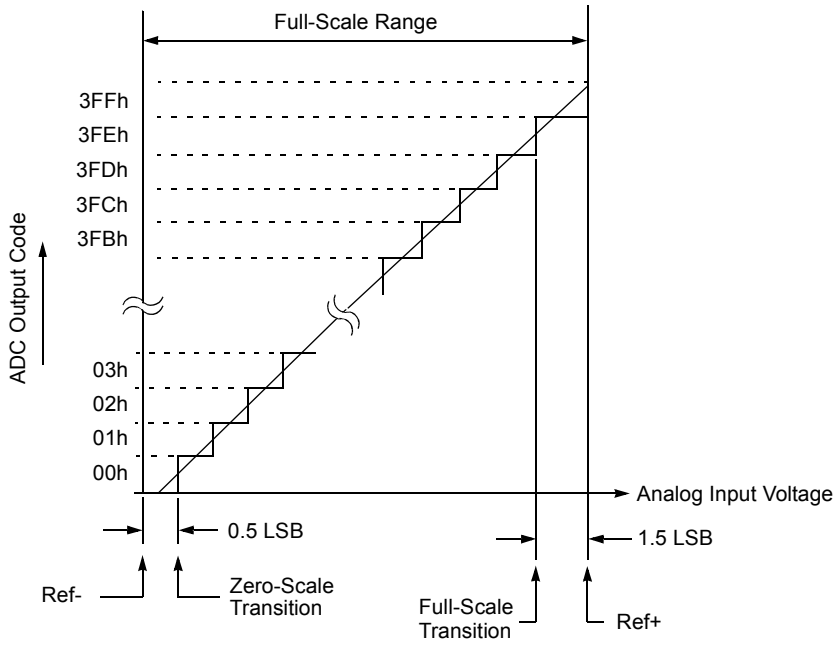


Legend: CHOLD = Sample/Hold Capacitance
CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to varies injunctions
RIC = Interconnect Resistance
RSS = Resistance of Sampling switch
SS = Sampling Switch
VT = Threshold Voltage
RS = Source Resistance



Note 1: See Refer to **Section 37.0 "Electrical Specifications"**.

FIGURE 20-5: ADC TRANSFER FUNCTION



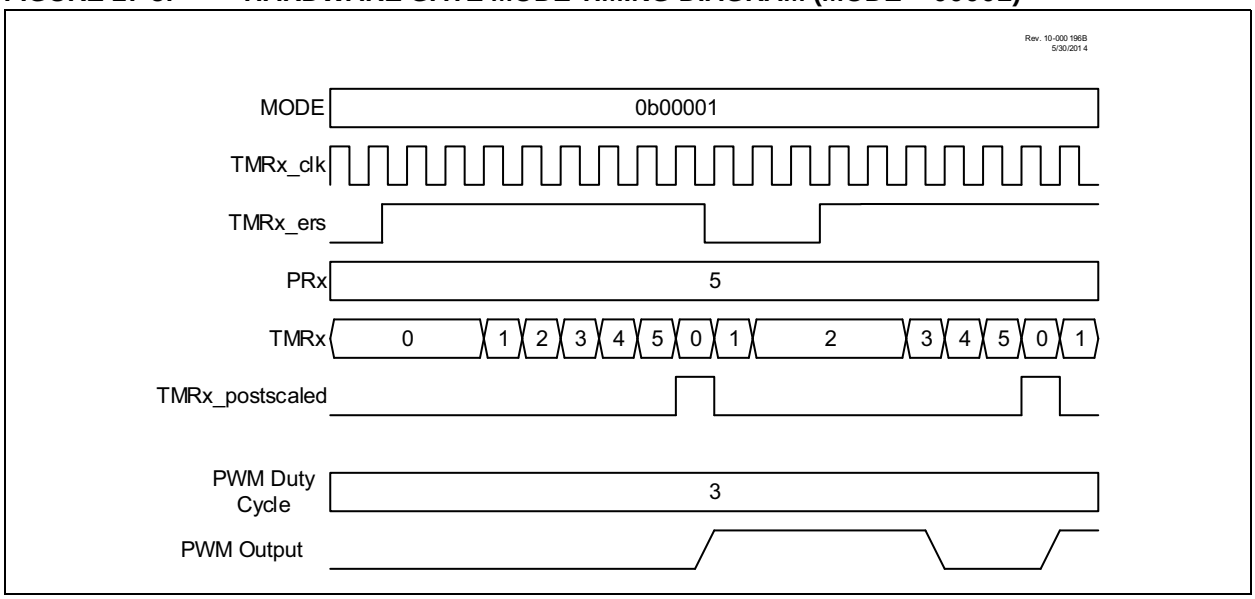
27.5.2 HARDWARE GATE MODE

The Hardware Gate modes operate the same as the Software Gate mode except the TMRx_ers external signal gates the timer. When used with the CCP the gating extends the PWM period. If the timer is stopped when the PWM output is high then the duty cycle is also extended.

When MODE<4:0> = 00001 then the timer is stopped when the external signal is high. When MODE<4:0> = 00010 then the timer is stopped when the external signal is low.

Figure 27-5 illustrates the Hardware Gating mode for MODE<4:0> = 00001 in which a high input level starts the counter.

FIGURE 27-5: HARDWARE GATE MODE TIMING DIAGRAM (MODE = 00001)



REGISTER 31-2: CLCxPOL: SIGNAL POLARITY CONTROL REGISTER

R/W-0/0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxPOL	—	—	—	LCxG4POL	LCxG3POL	LCxG2POL	LCxG1POL
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **LCxPOL:** CLCxOUT Output Polarity Control bit
1 = The output of the logic cell is inverted
0 = The output of the logic cell is not inverted

bit 6-4 **Unimplemented:** Read as ‘0’

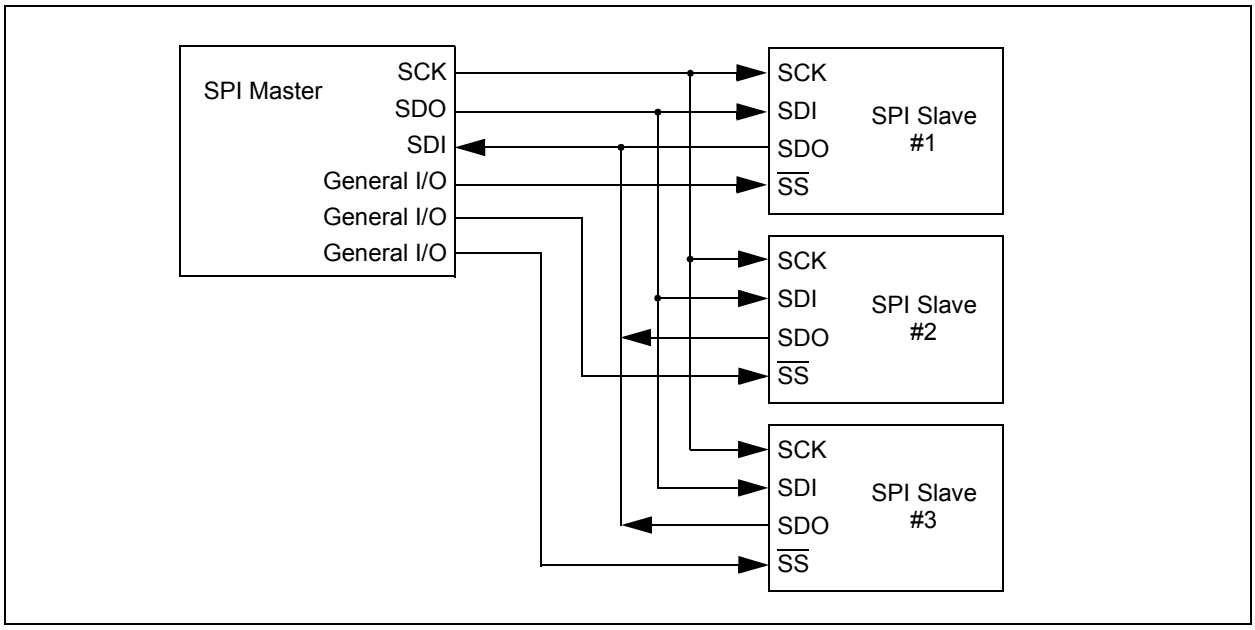
bit 3 **LCxG4POL:** Gate 3 Output Polarity Control bit
1 = The output of gate 3 is inverted when applied to the logic cell
0 = The output of gate 3 is not inverted

bit 2 **LCxG3POL:** Gate 2 Output Polarity Control bit
1 = The output of gate 2 is inverted when applied to the logic cell
0 = The output of gate 2 is not inverted

bit 1 **LCxG2POL:** Gate 1 Output Polarity Control bit
1 = The output of gate 1 is inverted when applied to the logic cell
0 = The output of gate 1 is not inverted

bit 0 **LCxG1POL:** Gate 0 Output Polarity Control bit
1 = The output of gate 0 is inverted when applied to the logic cell
0 = The output of gate 0 is not inverted

FIGURE 32-4: SPI MASTER AND MULTIPLE SLAVE CONNECTION



32.2.1 SPI MODE REGISTERS

The MSSP module has five registers for SPI mode operation. These are:

- MSSP STATUS register (SSPxSTAT)
- MSSP Control register 1 (SSPxCON1)
- MSSP Control register 3 (SSPxCON3)
- MSSP Data Buffer register (SSPxBUF)
- MSSP Address register (SSPxADD)
- MSSP Shift register (SSPxSR) (Not directly accessible)

SSPxCON1 and SSPxSTAT are the control and status registers in SPI mode operation. The SSPxCON1 register is readable and writable. The lower six bits of the SSPxSTAT are read-only. The upper two bits of the SSPxSTAT are read/write.

In one SPI master mode, SSPxADD can be loaded with a value used in the Baud Rate Generator. More information on the Baud Rate Generator is available in **Section 32.7 “Baud Rate Generator”**.

SSPxSR is the shift register used for shifting data in and out. SSPxBUF provides indirect access to the SSPxSR register. SSPxBUF is the buffer register to which data bytes are written, and from which data bytes are read.

In receive operations, SSPxSR and SSPxBUF together create a buffered receiver. When SSPxSR receives a complete byte, it is transferred to SSPxBUF and the SSPxIF interrupt is set.

During transmission, the SSPxBUF is not buffered. A write to SSPxBUF will write to both SSPxBUF and SSPxSR.

35.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process, allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- $\overline{MCLR}/V_{PP}$
- V_{DD}
- V_{SS}

In Program/Verify mode the program memory, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ICSPCLK pin is the clock input. For more information on ICSP™ refer to the **"***PIC16(L)F153XX Memory Programming Specification***"** (DS40001838).

35.1 High-Voltage Programming Entry Mode

The device is placed into High-Voltage Programming Entry mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on $\overline{MCLR}/V_{PP}$ to V_{IHH}.

35.2 Low-Voltage Programming Entry Mode

The Low-Voltage Programming Entry mode allows the PIC® Flash MCUs to be programmed using V_{DD} only, without high voltage. When the LVP bit of Configuration Words is set to '1', the low-voltage ICSP programming entry is enabled. To disable the Low-Voltage ICSP mode, the LVP bit must be programmed to '0'. The LVP bit can only be reprogrammed to '0' by using the High-Voltage Programming mode.

Entry into the Low-Voltage Programming Entry mode requires the following steps:

1. $\overline{MCLR}$ is brought to V_{IL}.
2. A 32-bit key sequence is presented on ICSPDAT, while clocking ICSPCLK.

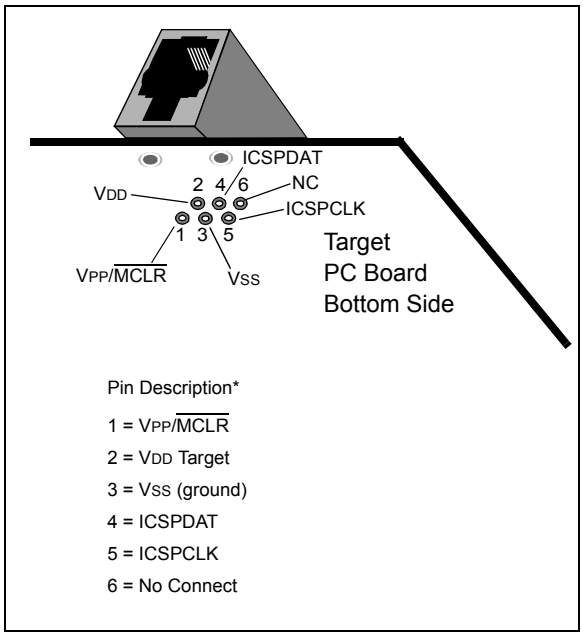
Once the key sequence is complete, $\overline{MCLR}$ must be held at V_{IL} for as long as Program/Verify mode is to be maintained.

If low-voltage programming is enabled (LVP = 1), the $\overline{MCLR}$ Reset function is automatically enabled and cannot be disabled. See **Section 8.5"MCLR"** for more information.

35.3 Common Programming Interfaces

Connection to a target device is typically done through an ICSP™ header. A commonly found connector on development tools is the RJ-11 in the 6P6C (6-pin, 6-connector) configuration. See Figure 35-1.

FIGURE 35-1: ICD RJ-11 STYLE CONNECTOR INTERFACE



Another connector often found in use with the PICkit™ programmers is a standard 6-pin header with 0.1 inch spacing. Refer to Figure 35-2.

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 35-3 for more information.

FIGURE 37-7: CLKOUT AND I/O TIMING

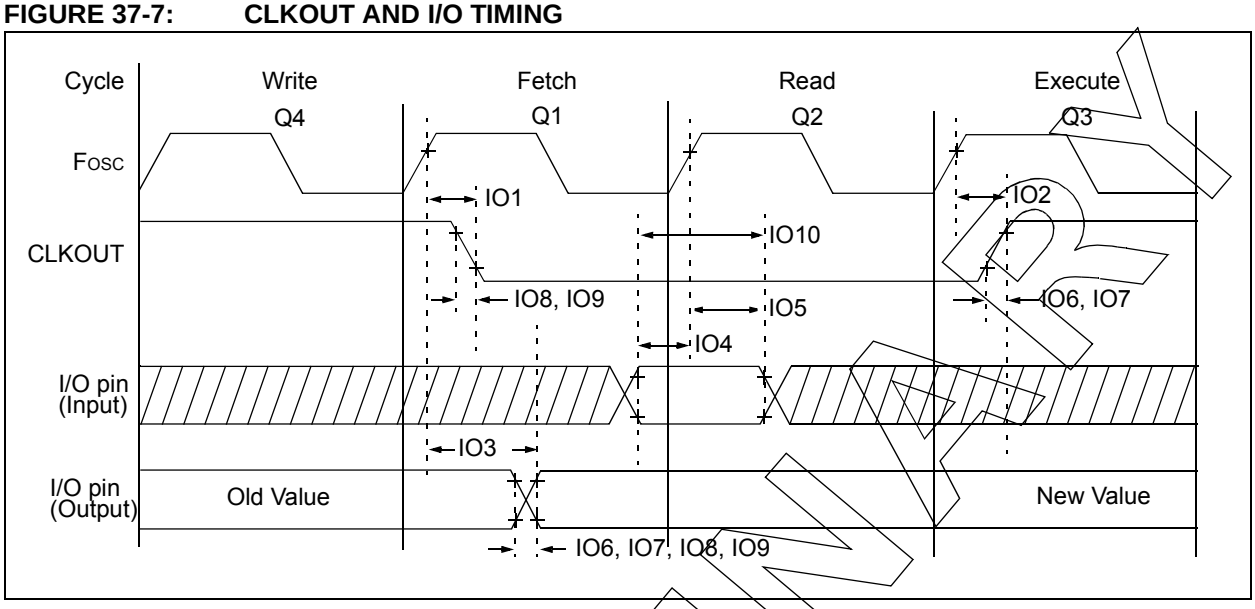


TABLE 37-10: I/O AND CLKOUT TIMING SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
IO1*	$T_{CLKOUTH}$	CLKOUT rising edge delay (rising edge Fosc (Q1 cycle) to falling edge CLKOUT	—	—	70	ns	
IO2*	$T_{CLKOUTL}$	CLKOUT falling edge delay (rising edge Fosc (Q3 cycle) to rising edge CLKOUT	—	—	72	ns	
IO3*	T_{IO_VALID}	Port output valid time (rising edge Fosc (Q1 cycle) to port valid)	—	50	70	ns	
IO4*	T_{IO_SETUP}	Port input setup time (Setup time before rising edge Fosc – Q2 cycle)	20	—	—	ns	
IO5*	T_{IO_HOLD}	Port input hold time (Hold time after rising edge Fosc – Q2 cycle)	50	—	—	ns	
IO6*	T_{IOR_SLREN}	Port I/O rise time, slew rate enabled	—	25	—	ns	V_{DD} = 3.0V
IO7*	T_{IOR_SLRDIS}	Port I/O rise time, slew rate disabled	—	5	—	ns	V_{DD} = 3.0V
IO8*	T_{IOF_SLREN}	Port I/O fall time, slew rate enabled	—	25	—	ns	V_{DD} = 3.0V
IO9*	T_{IOF_SLRDIS}	Port I/O fall time, slew rate disabled	—	5	—	ns	V_{DD} = 3.0V
IO10*	T_{INT}	INT pin high or low time to trigger an interrupt	25	—	—	ns	
IO11*	T_{IOC}	Interrupt-on-Change minimum high or low time to trigger interrupt	25	—	—	ns	

*These parameters are characterized but not tested.

39.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

39.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®